

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	Printed Circuit Board with Isolated Metallic Substrate Comprising an Integrated Cooling System
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Application Number :

Confirmation Number:

First Named Applicant: Carles Borrego Bel

Attorney Docket Number: 8134ES

Art Unit:

Examiner:

Search string: ( 6226178 or 5875097 or 6219246 or 6212071 or 6190941 or 6032355 or 6201300  
or 6201701 ),pn

Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

## US Patent Documents

**Note:** Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
<i>K</i>	1	6226178	2001-05-01	Border et al	B1	361	687
<i>K</i>	2	5875097	1999-02-23	Amaro et al	A	361	704
<i>K</i>	3	6219246	2001-04-17	Edevold et al	B1	361	707
<i>K</i>	4	6212071	2001-04-03	Roessler et al	B1	361	704
<i>K</i>	5	6190941	2001-02-20	Heinz et al	B1	438	106
<i>K</i>	6	6032355	2000-03-07	Tseng et al	A	29	840
<i>K</i>	7	6201300	2001-03-13	Tseng et al	B1	257	706
<i>K</i>	8	6201701	2001-03-13	Linden et al	B1	361	720

## Signature

Examiner Name	Date
<i>Sam H. Og...</i>	<i>12/16/05</i>